

### Thermal Characteristics

Package	$I_D$ (continuous) <sup>†</sup> (mA)	$I_D$ (pulsed) <sup>†</sup> (A)	Power Dissipation @ $T_c = 25^\circ\text{C}$ (W)	$\theta_{ja}$ ( $^\circ\text{C}/\text{W}$ )	$I_{DR}$ (mA)	$I_{DRM}^{\dagger}$ (A)
8-Lead SOIC	-700	-1.25	1.5 <sup>‡</sup>	101 <sup>‡</sup>	-700	-1.25
TO-92	-500	-1.25	1.0	132	-500	-1.25

**Notes:**

- <sup>†</sup>  $I_D$  (continuous) is limited by max rated  $T_r$ .
- <sup>‡</sup> Mounted on FR4 board, 25mm x 25mm x 1.57mm

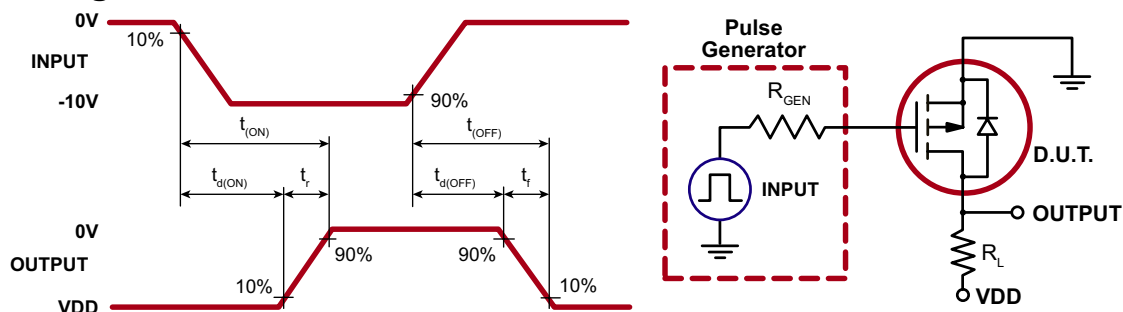
### Electrical Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise specified)

Sym	Parameter	Min	Typ	Max	Units	Conditions
$BV_{DSS}$	Drain-to-source breakdown voltage	-16.5	-	-	V	$V_{GS} = 0V, I_D = -1.0mA$
$V_{GS}$	Gate threshold voltage	-0.5	-0.7	-1.0	V	$V_{GS} = V_{DS}, I_D = -1.0mA$
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-	-4.0	mV/ $^\circ\text{C}$	$V_{GS} = V_{DS}, I_D = -1.0mA$
$I_{GSS}$	Gate body leakage	-	-	-100	nA	$V_{GS} = \pm 10V, V_{DS} = 0V$
$I_{DSS}$	Zero gate voltage drain current	-	-	-100	nA	$V_{DS} = -15V, V_{GS} = 0V$
$I_{D(ON)}$	On-state drain current	-	-0.4	-	A	$V_{GS} = V_{DS} = -2.0V$
		-0.6	-1.0	-		$V_{GS} = V_{DS} = -3.0V$
		-1.25	-2.30	-		$V_{GS} = V_{DS} = -5.0V$
$R_{DS(ON)}$	Static drain-to-source on-state resistance	-	2.0	4.0	$\Omega$	$V_{GS} = -2.0V, I_D = -50mA$
		-	1.7	2.0		$V_{GS} = -3.0V, I_D = -150mA$
		-	1.3	1.5		$V_{GS} = -5.0V, I_D = -300mA$
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	-	-	0.75	%/ $^\circ\text{C}$	$V_{GS} = -5.0V, I_D = -300mA$
$G_{FS}$	Forward transconductance	500	700	-	mmho	$V_{GS} = -15V, I_D = -1.0A$
$C_{ISS}$	Input capacitance	-	120	250	pF	$V_{GS} = 0V,$ $V_{DS} = -15V,$ $f = 1.0MHz$
$C_{OSS}$	Common source output capacitance	-	100	125		
$C_{RSS}$	Reverse transfer capacitance	-	40	60		
$t_{d(ON)}$	Turn-on delay time	-	-	20	ns	$V_{DD} = -15V,$ $I_D = -1.25A,$ $R_{GEN} = 25\Omega$
$t_r$	Rise time	-	-	20		
$t_{d(OFF)}$	Turn-off delay time	-	-	30		
$t_f$	Fall time	-	-	30		
$V_{SD}$	Diode forward voltage drop	-	-1.2	-1.5	V	$V_{GS} = 0V, I_{SD} = -500mA$

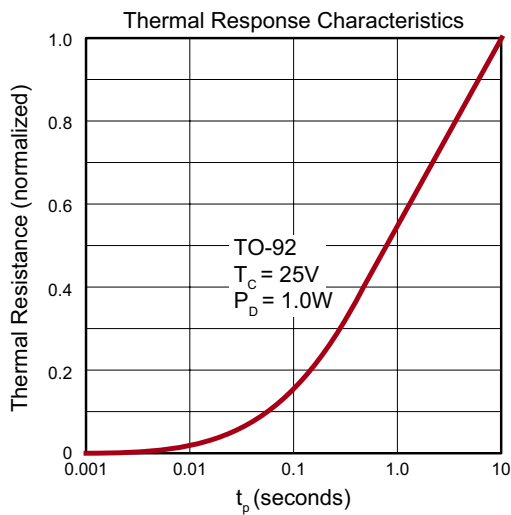
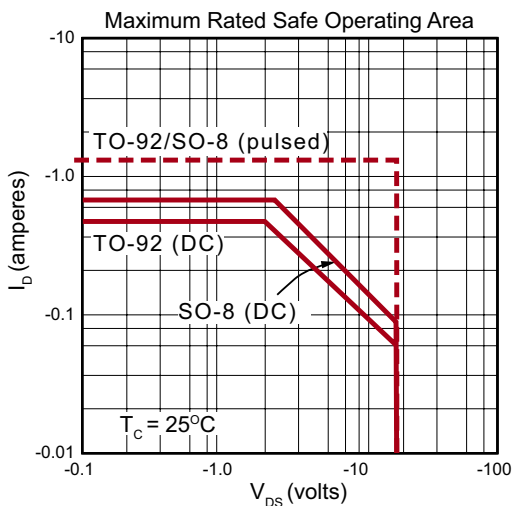
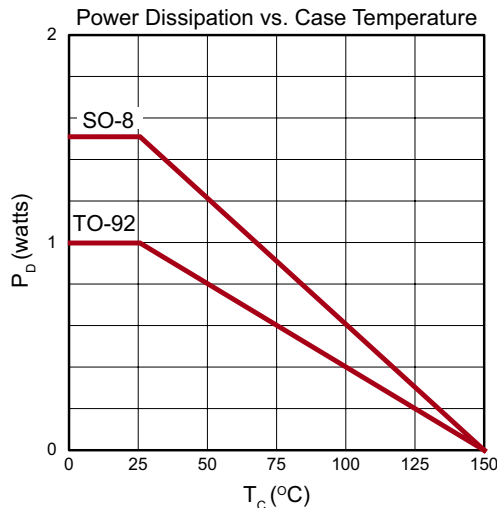
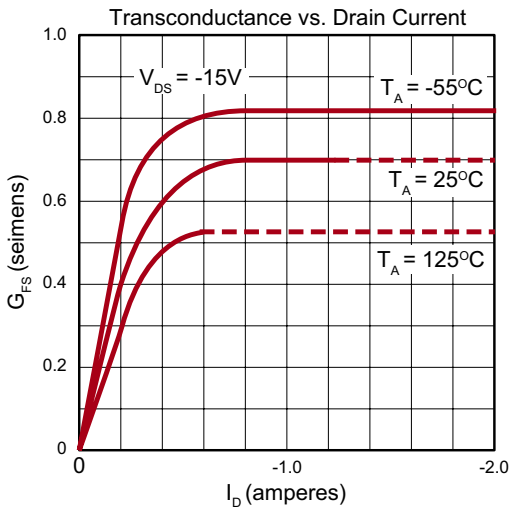
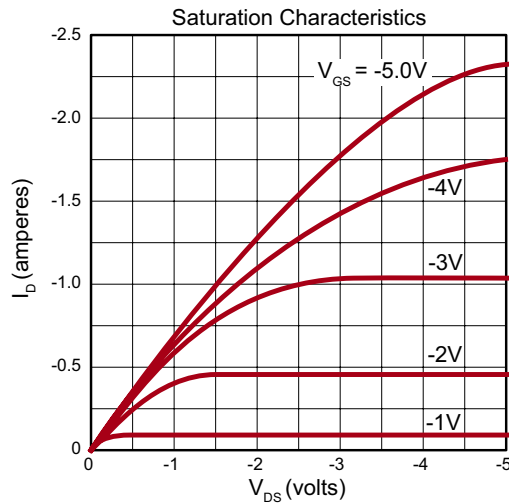
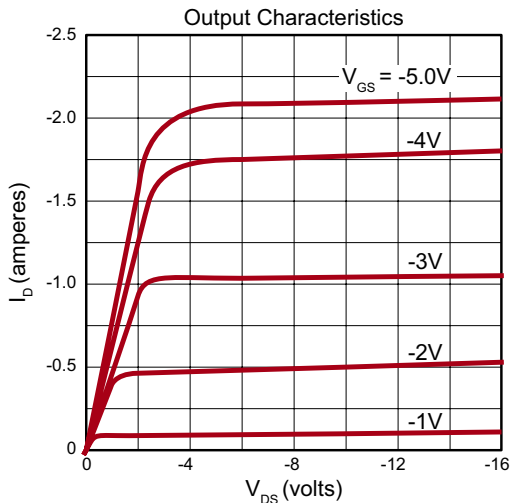
**Notes:**

1. All D.C. parameters 100% tested at 25 $^\circ\text{C}$  unless otherwise stated. (Pulse test: 300 $\mu\text{s}$  pulse, 2% duty cycle.)
2. All A.C. parameters sample tested.

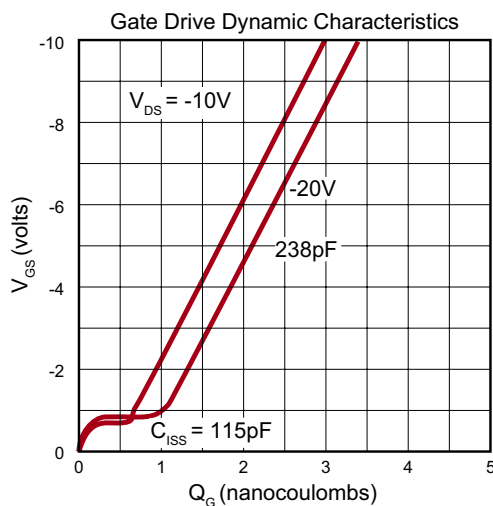
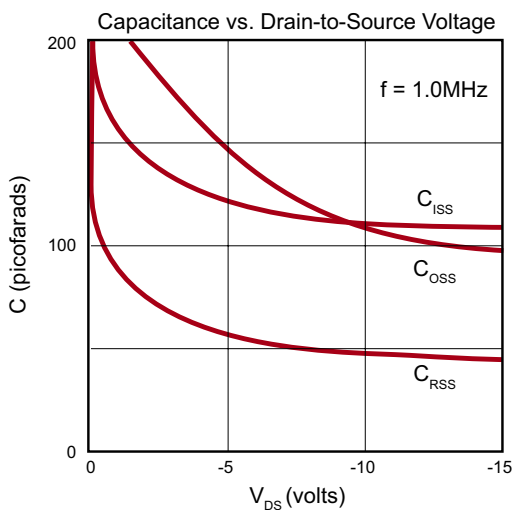
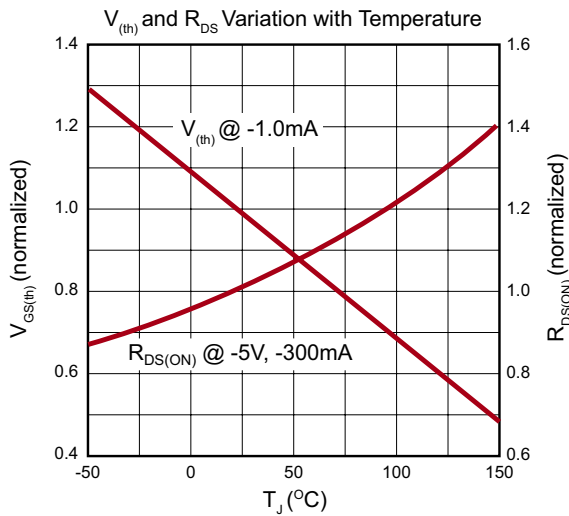
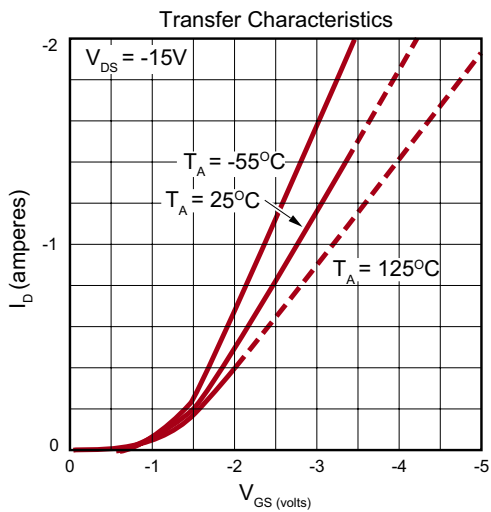
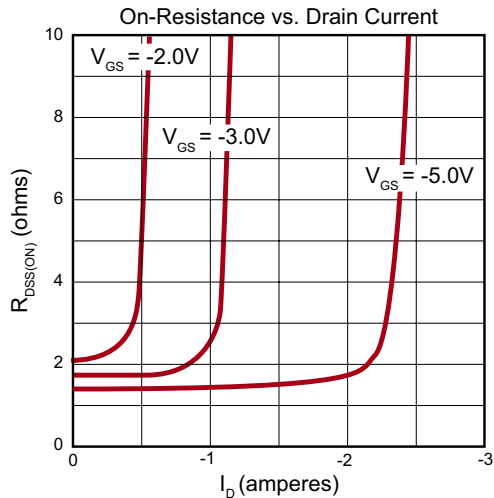
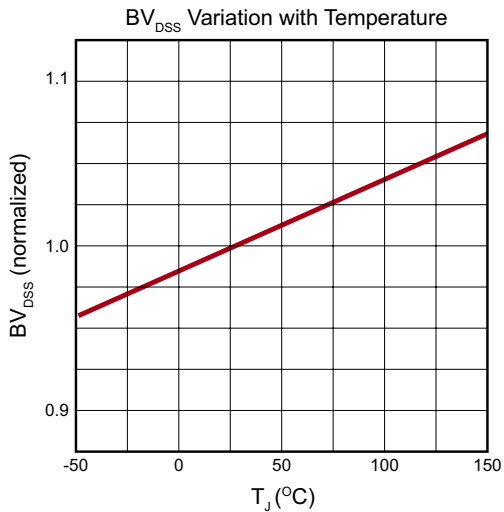
### Switching Waveforms and Test Circuit



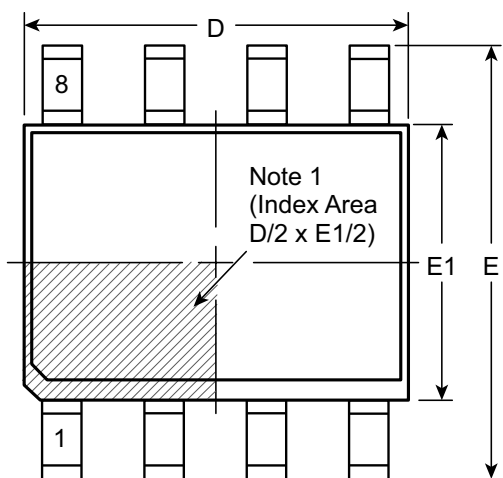
# Typical Performance Curves



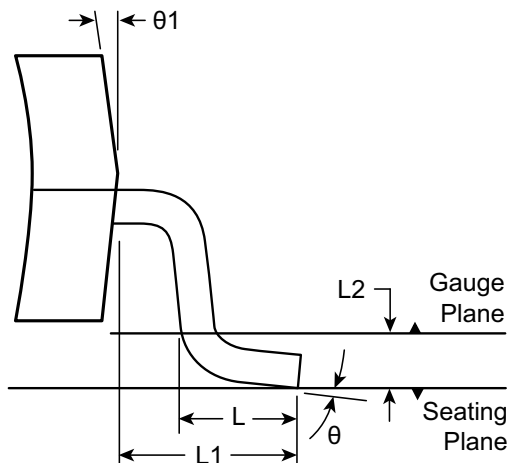
Typical Performance Curves (cont.)



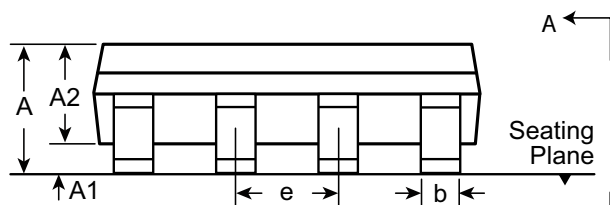
# 8-Lead SOIC (Narrow Body) Package Outline (LG)



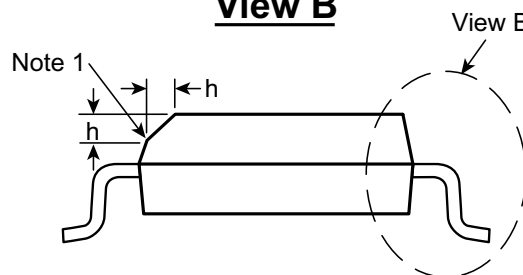
**Top View**



**View B**



**Side View**



**View A-A**

**Note:**  
 1. This chamfer feature is optional. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbol	A	A1	A2	b	D	E	E1	e	h	L	L1	L2	θ	θ1		
Dimension (mm)	MIN	1.35*	0.10	1.25	0.31	4.80*	5.80*	3.80*	1.27 BSC	0.25	0.40	1.04 REF	0.25	0°	5°	
	NOM	-	-	-	-	4.90	6.00	3.90		-	-		-			-
	MAX	1.75	0.25	1.65*	0.51	5.00*	6.20*	4.00*		0.50	1.27		0.25 BSC			8°

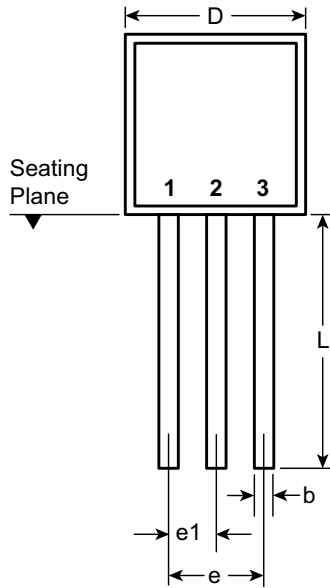
JEDEC Registration MS-012, Variation AA, Issue E, Sept. 2005.

\* This dimension is not specified in the JEDEC drawing.

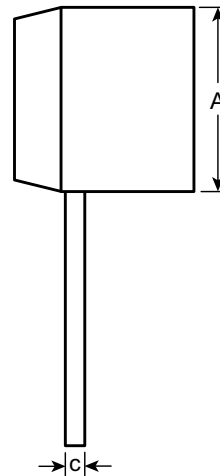
Drawings are not to scale.

Supertex Doc. #: DSPD-8SOLGTG, Version I041309.

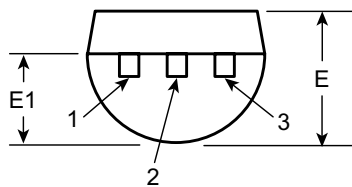
### 3-Lead TO-92 Package Outline (N3)



**Front View**



**Side View**



**Bottom View**

Symbol		A	b	c	D	E	E1	e	e1	L
Dimensions (inches)	MIN	.170	.014 <sup>†</sup>	.014 <sup>†</sup>	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 <sup>†</sup>	.022 <sup>†</sup>	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

\* This dimension is not specified in the JEDEC drawing.

† This dimension differs from the JEDEC drawing.

Drawings not to scale.

Supertex Doc.#: DSPD-3TO92N3, Version E041009.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <http://www.supertex.com/packaging.html>.)

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